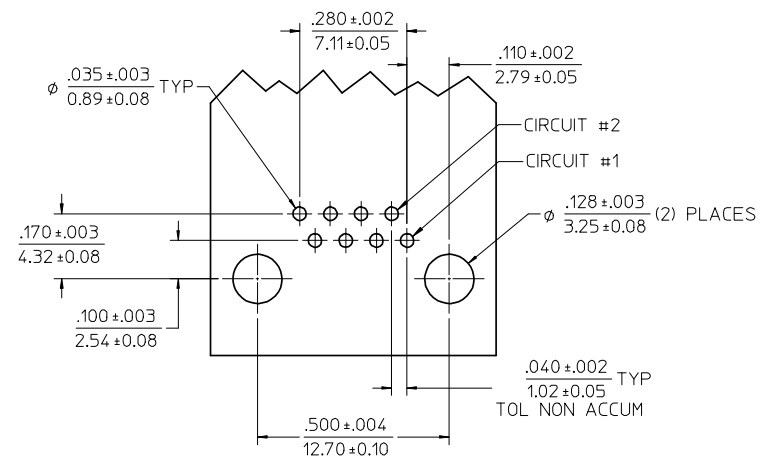
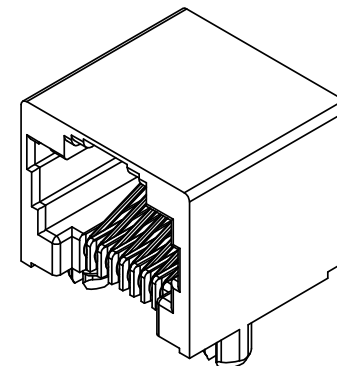
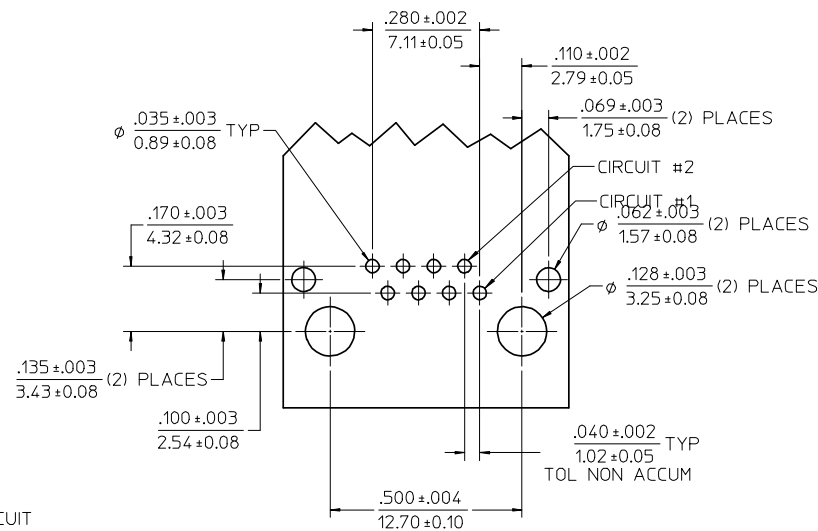
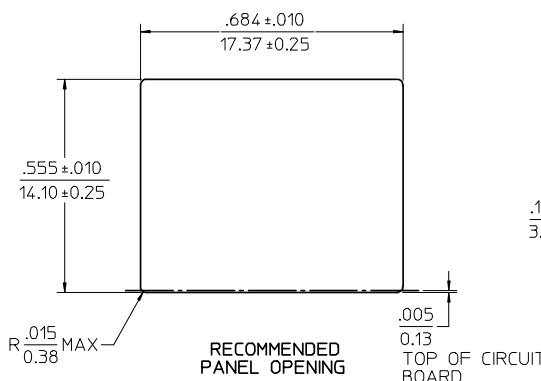
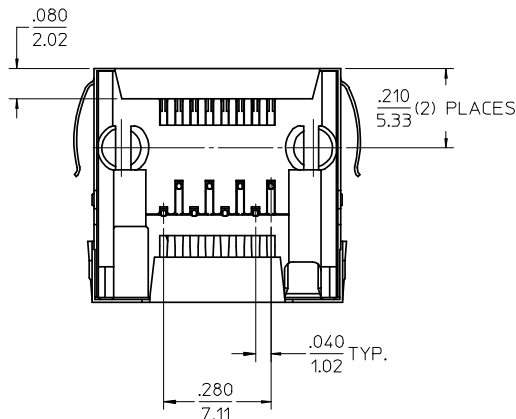
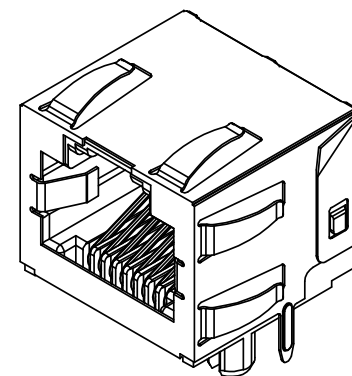
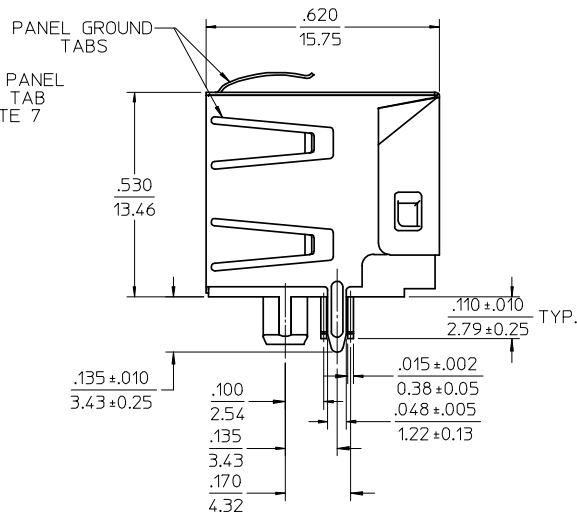
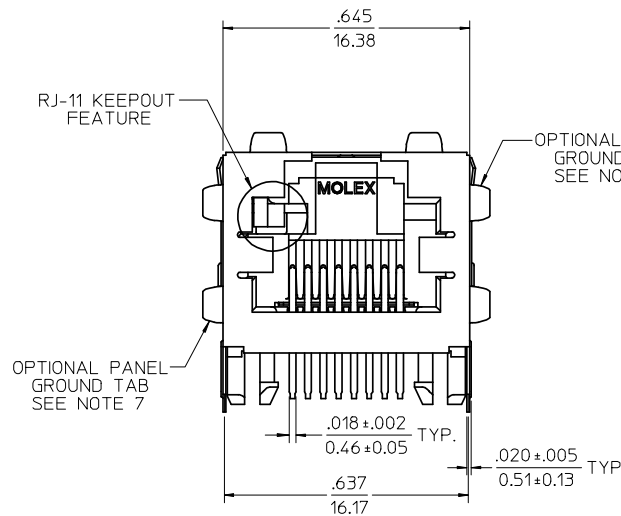




PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

ADD NOTE 7 EC NO: UCP2008-0965 DRWN:JBELL 2007/11/08 CHKD:LSCHMIT 2007/12/04 APPR:FSMITH 2007/12/05	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		▽=0 ◻=0	mmINCH	DRAWN BY DATE MKAMAR 00/03/07	TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE			
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	CHECKED BY DATE MKAMAR 00/03/07				
			ANGULAR ±1/2°	APPROVED BY DATE JROBERTS 00/03/07	MOLEX MOLEX INCORPORATED			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. 446200001	DOCUMENT NO. SD-44620-001		SHEET NO. 1 OF 4	
D2	REV			SIZE ()	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/157

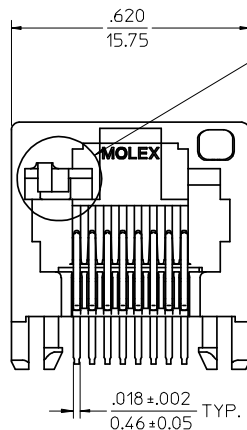
- NOTES:
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX
PACKAGING SPECIFICATION PK-43860-005.
 - 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR
SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.

ADD NOTE 8	EC NO: UCP2008-0965	DRWN: BELL	2007/11/08	CHKD: LSCMIDT	2007/12/04	APPR: FSMITH	2007/12/05	REV	DESCRIPTION	QUALITY SYMBOLS
D2										

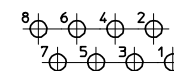
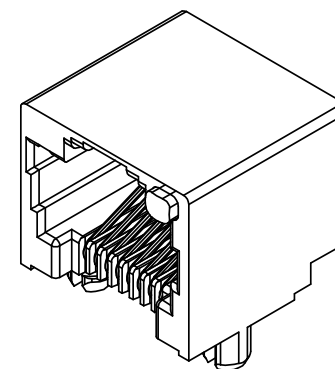
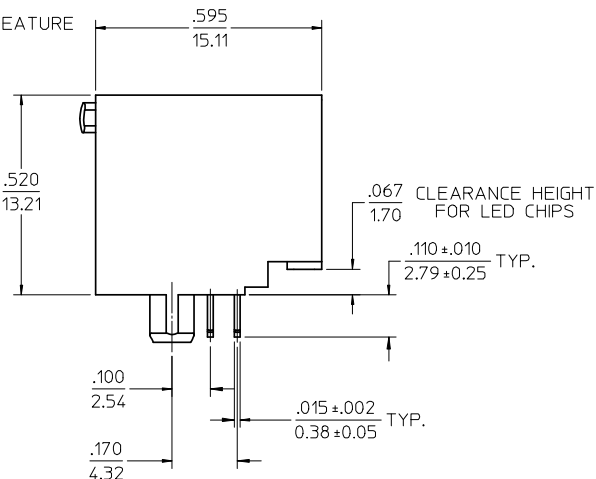
GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± ---	± ---
1 PLACE ± ---	± ---
ANGULAR ± 1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
IN/MM	
DRAWN BY	DATE
DATE	DATE
CHECKED BY	DATE
DATE	DATE
APPROVED BY	DATE
DATE	DATE
MATERIAL NO.	DOCUMENT NO.
DATE	DATE

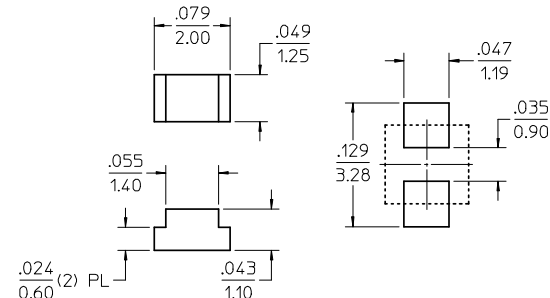
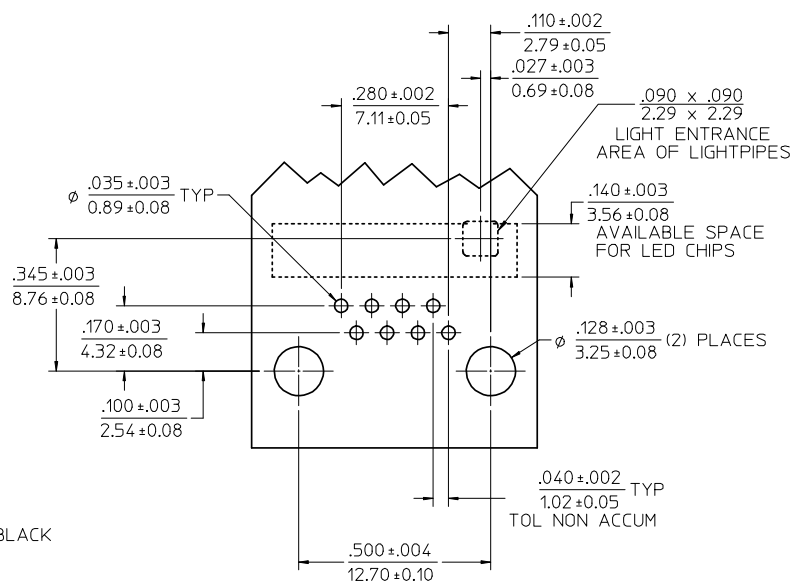
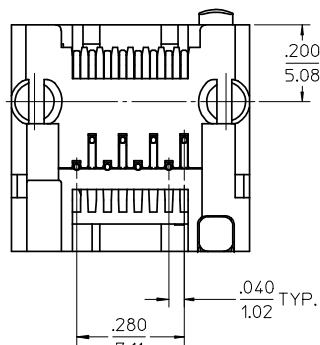
SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
4:1	INCH	
RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
MOLEX INCORPORATED		
SD-44620-001		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



RJ-11 KEEPOUT FEATURE



TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 8)

PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/1.57

NOTES:

- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
LIGHT PIPES:
POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX PACKAGING SPECIFICATION PK-43860-004.
- 5) APPLICATION SPECIFICATION: AS-43860-001
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

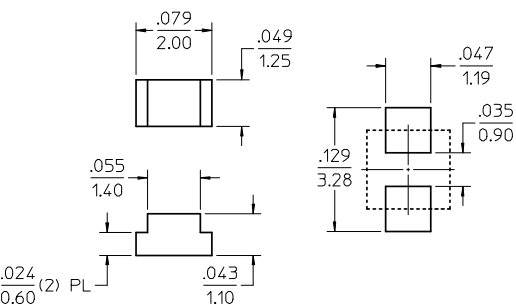
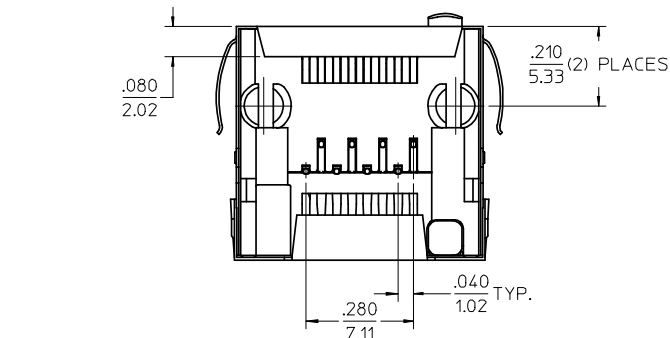
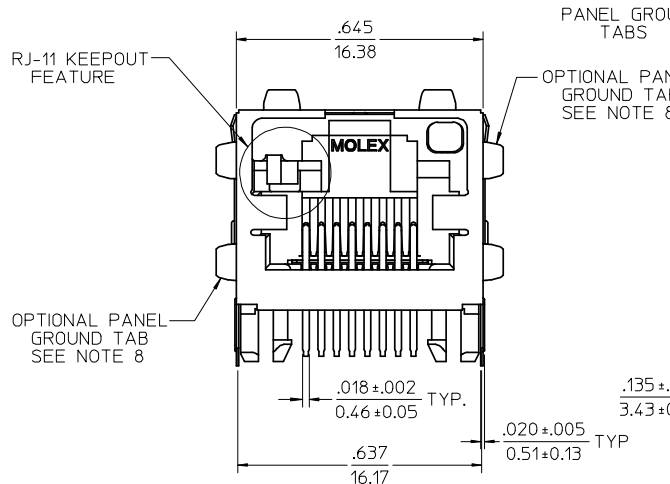
ADD NOTE 5 & 9	
EC NO: UCP2008-0965	2007/11/08
DRWN:JBELL	2007/12/04
CHKD:LSCHMIDT	2007/12/05
APPR:FSMITH	
REV	DESCRIPTION
D2	

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± ---	± ---
1 PLACE ± ---	± ---
ANGULAR ± 1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE IN/MM	
DRAWN BY	DATE
DATE	DATE
CHECKED BY	DATE
DATE	DATE
APPROVED BY	DATE
DATE	DATE
MATERIAL NO.	
SEE CHART	
SIZE	

SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
TITLE RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
 MOLEX INCORPORATED		
DOCUMENT NO. SD-44620-001		SHEET NO. 3 OF 4
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

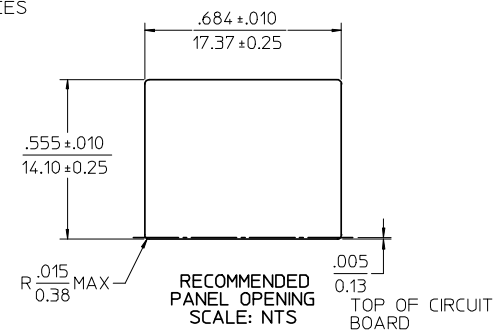
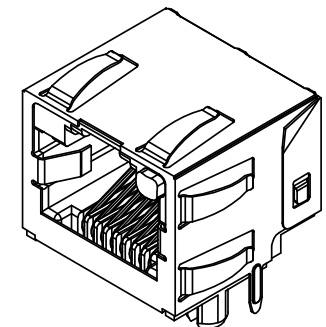


RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 10:1
(SEE NOTE 9)

TYPICAL PC TERMINAL HOLE LAYOUT
SCALE 5:1

PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS: .062/157

- NOTES:
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
LIGHT PIPES:
POLYCARBONATE-WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R
REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
POLYSULFONE-MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
*100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.
 - 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - 4) PACKAGING SPECIFICATION: CONNECTOR ASSEMBLIES PACKAGED IN
THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
 - 5) APPLICATION SPECIFICATION: AS-43860-001
 - 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE
TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - 9) FOR CROSS REFERENCE OF RECOMMENDED LED'S, SEE MOLEX WEBSITE.
 - 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



ASSEMBLY MATERIAL NUMBER	LIGHT PIPE MATERIAL	PANEL GROUND TABS
446201006	POLYCARBONATE	ALL
446201007	POLYCARBONATE	SEE NOTE 8
446201008	POLYSULFONE	ALL
446201009	POLYSULFONE	SEE NOTE 8

REV	DESCRIPTION	DATE
D2	ADD NOTE 5 & 10 EC NO: UCP2008-0965 DRWN: BELL CHKD: SCHMIDT APPR: FSMITH	2007/11/08 2007/12/04 2007/12/05

GENERAL TOLERANCES (UNLESS SPECIFIED)
4 PLACES ± .005
3 PLACES ± .004
2 PLACES ± .003
1 PLACE ± .002
ANGULAR ± 1/2°
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE IN/MM
DRAWN BY MKAMAR
CHECKED BY MKAMAR
APPROVED BY JROBERTS
MATERIAL NO. SEE CHART
DATE 00/03/07

SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
RJ-45 INVERTED MODULAR JACK ASSEMBLY WITH RJ-11 KEEPOUT FEATURE		
MOLEX INCORPORATED		
DOCUMENT NO. SD-44620-001	SHEET NO. 4 OF 4	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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www.lifeelectronics.ru